Abstract

A switching circuit is provided on a high frequency line forming a switch (SW). A plurality of switching circuits are provided for each high frequency line. A plurality of switching circuits provided at the same position are set as shunt circuits (S1, S2). In addition to providing a plurality of switching circuits at the same position, by separately providing a drive circuit for each switching circuit, the reliability can be improved. With a multiple-step structure in which a plurality of switching circuits are provided at different positions on the high frequency line, isolation between input and output is improved. By using a semiconductor element such as a PIN diode as a switching element within a switching circuit, it is possible to reduce numbers of maintenance services and maintenance personnel to facilitate usage, to reduce the size and cost, and to achieve high speed. By introducing a U-link in which a switching circuit and peripheral structures are made into a unit with a rigid line, the ease of maintenance and handling can be improved.